

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	535	438/108.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 16:07
L3	1	"6441495".pn.	US-PGPUB; USPAT; EPO	OR	ON	2006/05/12 16:09
L4	252	438/109.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 16:35
S62	454	(multidie or multi-die or stacked near die) near2 package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 10:27
S63	228	(interposer or substrate or package) near2 (recess or opening or indent or aperture or recessed or depression or depressed or receptacle) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 10:53
S64	192	(interposer or substrate or package) near2 (cavity) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:08
S65	455	(interposer) and (opening or aperture or hole or thruhole or cavity) near3 (wirebond or wire or wiring or bond) and (multichip or (stacked or plural or multi or multiple or plurality or second or two or third or three) near (chip or die or ic))	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 11:23
S67	312	(interposer or substrate) near10 (aperture or opening or hole or window) near3 ((wire or wiring) near (bond or bonding) or wirebonds) near5 (chip or die or ic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:07

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S68	193	(interposer or carrier near substrate) and (mcm or multichip or multichip or (plural or multiple or stacked or plurality or multi or bottom or back) near2 (chip or die or ic or module)) and (interposer or carrier or substrate) near2 (aperture or opening or recess or receptacle or window) near2 (chip or die or ic or wirebond or bonding near wire or wire near bond or pillar or interconnect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:33
S70	463	257/723.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:48
S71	272	257/724.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 13:18
S72	142	257/782.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 13:22
S74	369	257/786.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 13:31

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S75	32	(US-20040009631-\$ or US-20030085463-\$ or US-20040084771-\$ or US-20040159955-\$ or US-20020074630-\$ or US-20010004128-\$ or US-20030207516-\$ or US-20020127770-\$ or US-20030025199-\$ or US-20020047196-\$ or US-20010036711-\$ or US-20020079568-\$ or US-20020109237-\$).did. or (US-6791195-\$ or US-6388333-\$ or US-6448506-\$ or US-5477082-\$ or US-6731015-\$ or US-6506633-\$ or US-5886412-\$ or US-6343019-\$ or US-5608262-\$ or US-6452278-\$ or US-5949135-\$ or US-5869894-\$ or US-6693362-\$ or US-6104089-\$ or US-6365963-\$ or US-6678167-\$ or US-6659512-\$ or US-5963794-\$).did. or (EP-1122786-\$).did.	US-PGPUB; USPAT; EPO	OR	ON	2006/05/12 16:08
S76	179	film near3 substrate near10 (tab or tape near automated near bonding) same (rigid\$4 or flex\$4 or lead or metal)	US-PGPUB; USPAT; EPO	OR	ON	2006/05/12 14:34
S77	25	("5564617" "5671530" "5723369" "5760478" "5790384" "5798567" "5801072" "5804882" "6084308" "6098278" "6150724" "6189208" "6190940" "6201301" "6225699" "6271598" "6291267" "6292368" "6294406" "6365963" "6369448" "6489669" "6489686" "6492726" "6521984").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 14:20
S78	1	"5977640".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 14:20
S79	1	"6906415".pn.	US-PGPUB; USPAT; EPO	OR	ON	2006/05/12 14:31
S81	96	(film or tape or resin or polyimide) near3 (substrate or carrier) near15 (tab or tape near automated near bonding) same (rigid\$4)	US-PGPUB; USPAT; EPO	OR	ON	2006/05/12 14:37
S83	27	(film or tape or resin or polyimide) near3 (substrate or carrier or interposer) near3 (rigid\$4) near15 (tab or tape near automated near bonding)	US-PGPUB; USPAT; EPO	OR	ON	2006/05/12 14:47

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S84	6	US-5926029-\$.DID. OR US-6100804-\$. DID. OR US-6395578-\$.DID. OR US-6762078-\$.DID. OR US-6798049-\$. DID. or "6515356".pn.	US-PGPUB; USPAT; EPO	OR	ON	2006/05/12 14:48
S85	435	438/107.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 14:57